

ABSTRACT OF THE DISCLOSURE

**TITLE OF INVENTION: MOUNTING APPARATUS FOR
ELECTRONIC COMPONENT**

An apparatus is provided with a component feeding member for feeding electronic components having lead wires in a tape-bonded state, an insertion head for separating the electronic components fed from the feeding member from the tapes and inserting to holes of a board, and a fixing head facing the insertion head via the board for cutting and folding the lead wires of the inserted electronic component in the board thereby fixing the electronic component to the board. AC servo motors operating independently of each other are individually set in the insertion head and the fixing head, which are controlled by a device so as to be synchronous with each other.

Figure 1